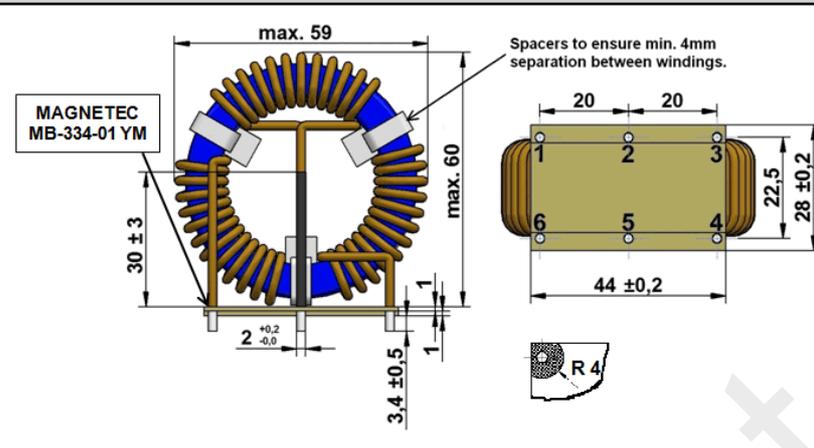
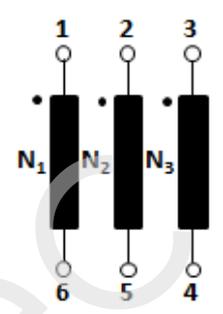


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<b>Client:</b>	<b>MAGNETEC</b>	<b>Magnetec P/N:</b>	<b>MB-334</b>	
<b>Client's p/n:</b>		<b>PS Index:</b>	<b>01</b>	<b>PS Revision:</b> 04
<b>Subject:</b>	<b>EMC Component</b>			

1. Mechanical outline	Wiring diagram
 <p style="margin-top: 10px;">Tolerances: +/- 0,3mm                  The pins # 1, 3, 4, 6 are fixed by soldering (pretinned copper pad diameter 8mm),                  the pins # 2, 5 by glue.</p>	

2. Nominal values			
Core material:	<b>NANOPERM®</b>	High voltage strength:	<b>Up,eff = 2,5 kV</b>
Nominal voltage:	<b>480 Veff AC</b>	Ambient temperature:	<b>-40 ... +60 °C</b>
Nominal inductance:	<b>3 x 1,7 mH</b>	Max. operating temperature:	<b>°C</b>
Nominal current:	<b>3 x 20 A</b>	Storage temperature:	<b>-40 ... +85 °C</b>
Leakage inductances:	<b>ca. 15 µH</b>	Design standard:	<b>EN 60938-1</b>
No. of turns:	<b>N1 = N2 = N3 = 13</b>	Wire diameter:	<b>2,0 mm</b>
Comments:	<b>Max. allowed choke surface temperature : +120°C</b>		

3. Inspection values (at room temperature, unless otherwise stated)			
Measured value	Measuring limits	Measuring configurations	
Inductivity L1; L2; L3 [mH]	1,1 - 2,7	f = 10 kHz	Ueff = 100 mV AC
Wire resistance Rcu1; Rcu2; Rcu3 [mOhms]	NA - 4,3	RT = 25°C	IDC = 10A
HV strength between N1; N2; N3 / Iiso < 1mA	OK - NOK	Up,eff = 2,5 kV	t = 2 s
Mechanical dimensions [mm]	OK - NOK		

4. Others	
Marking:	<b>MAGNETEC MB-334-01 YM (YM = Year/Month), acc. to IEC 60062 6.1.1</b>
Packaging:	<b>6 pcs. per layer, 4 layers per carton box; PU = 24 pcs.</b>
Comments:	Visit <a href="http://www.magnetec.de/fileadmin/pdf/pb_ds.pdf">http://www.magnetec.de/fileadmin/pdf/pb_ds.pdf</a> for further information.

Index / Rev.	Alteration	Date
01 / 01	Product Specification	30.11.2011
01 / 02	Leakage inductance modified	05.10.2012
01 / 03	Assembly and dimension change	21.02.2013
01 / 04	Change to paper based packaging	06.10.2016

<b>Created:</b>	Z. Palánki 06.10.2016	<b>Approved (Techn):</b>	F. Zámboreszky 10.10.2016	<b>Approved (Quality):</b>	L. Ferencz 10.10.2016	<b>Released:</b>	T. Trupp 10.10.2016
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